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**Design Guide for High
Density Interconnects (HDI)
and Microvias**

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A standard developed by IPC and JPCA

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Developed by the High Density Interconnect (HDI) Design Subcommittee (D-41) of the High Density Interconnect (HDI) Committee (D-40) of IPC and the Build-Up PWB Committee of the Japan Printed Circuit Association (JPCA)

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